

深圳市艾特诺通讯设备有限公司
SHENZHEN ATN COMMUNICATION TECHNOLOGY CO., LTD.
规 格 书
SPECIFICATION FOR APPROVL

编 号: ATN1608CHIP2440 天线
MODEL NO

规 格: 1.6*0.8*0.8mm
SPECIFICATIONS:

日 期: 2023.03.23
DATE:

深圳市艾特诺通讯设备有限公司 A T N			客 户 CUSTOMER		
制作 make	审核 examine	核准 Approver	结构 Structure	电子 Electronics	核准 Approver

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发行/变更记录				
发行/变更日期	变更原因	变更内容	版本	备注
2022. 08. 16	新版发行	新版发行	A1. 0	
2023. 03. 23	增加参考设计	增加参考设计②	A2. 0	

一、测试设备 Test Equipment&Conditions

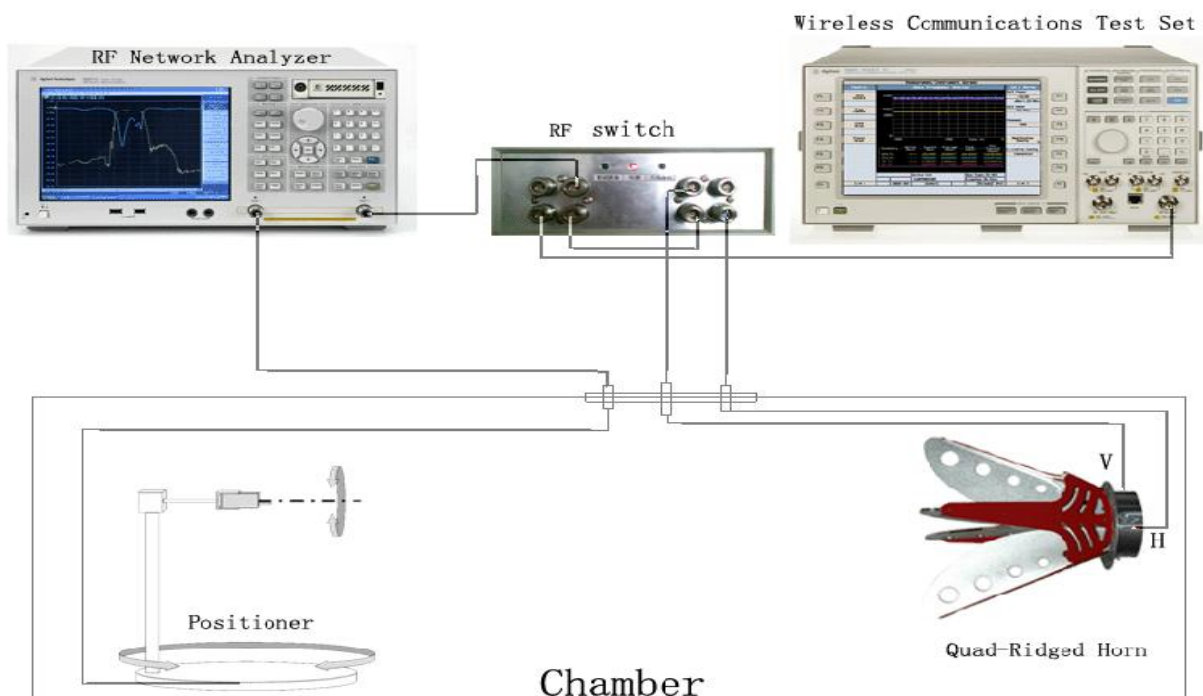
1.1 网络分析仪 (Network Analyzers)

Agilent Technologies E5071B

1.2 综合测试仪 (Communications Test Set)

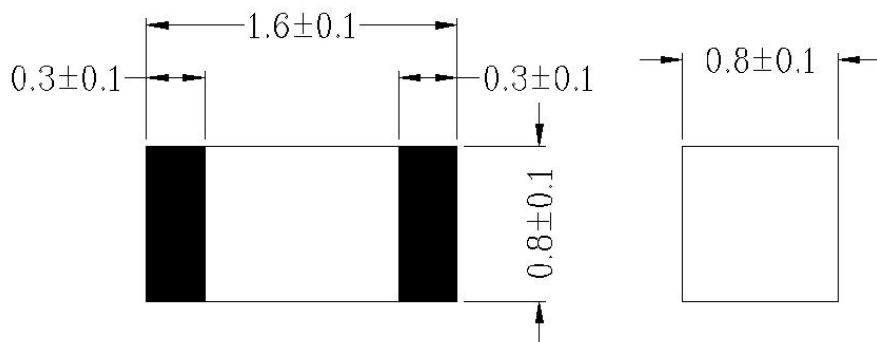
CMW500

1.3 3D 暗室测试系统 (3D Chamber Test System)



二、产品规格 Product Specification

2.1、尺寸规格



2.2、储存条件 Storage conditions

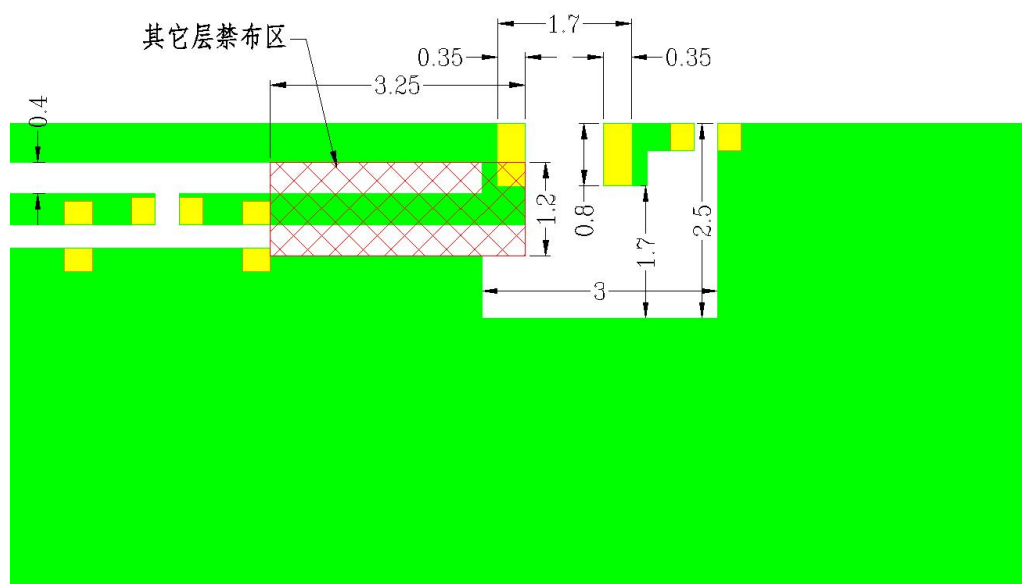
储存温度 Storage Temperature 5℃～40℃

相对湿度 relative humidity 20-70%

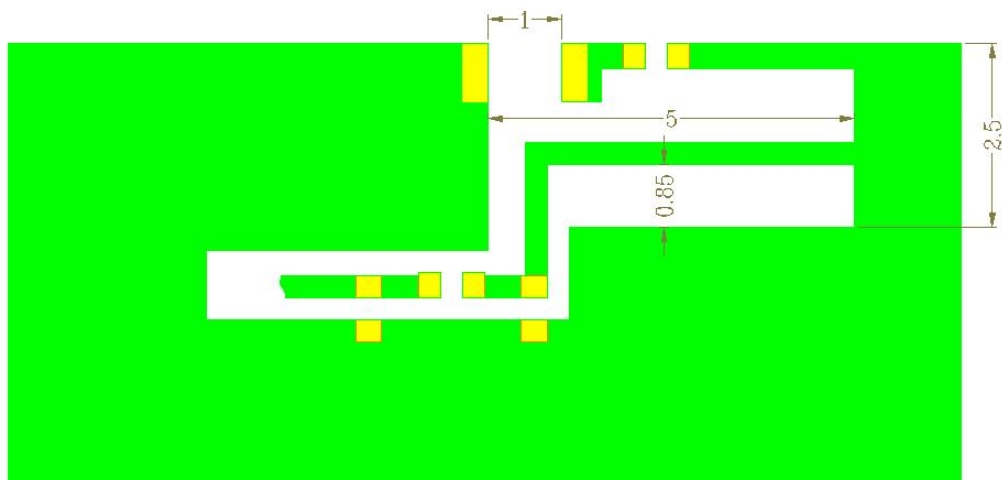
储存期限 Storage life 6 个月

三、参考设计 Reference design

①



②

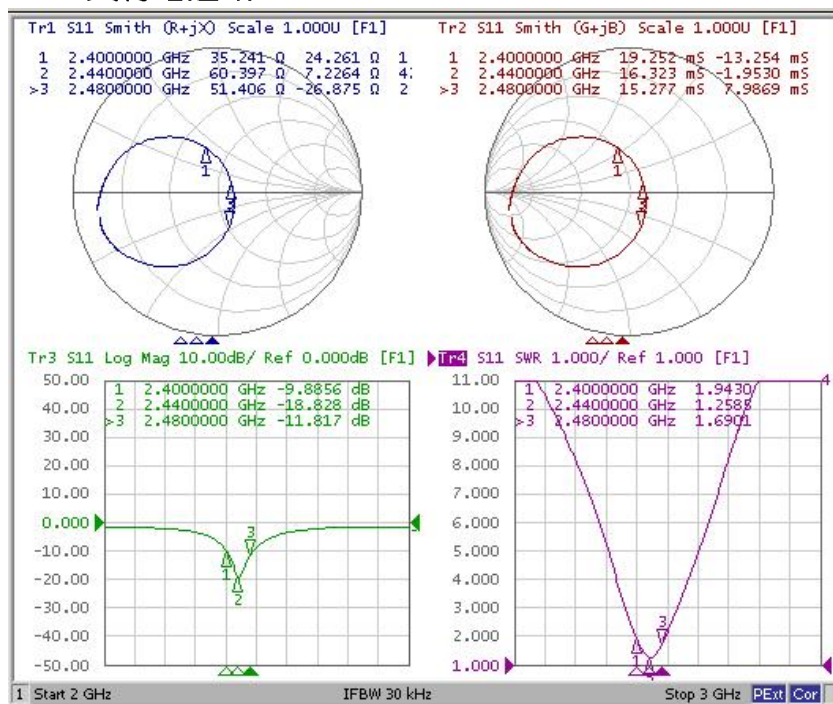


四、产品性能参数 Product performance parameters

Frequency	2400-2480MHz
VSRW	<2.0
Radiation efficiency	68%
Peak gain	3.2dBi
Polarization	Linear
Impedance	50 Ω

五、测试数据报告 Test Data Report

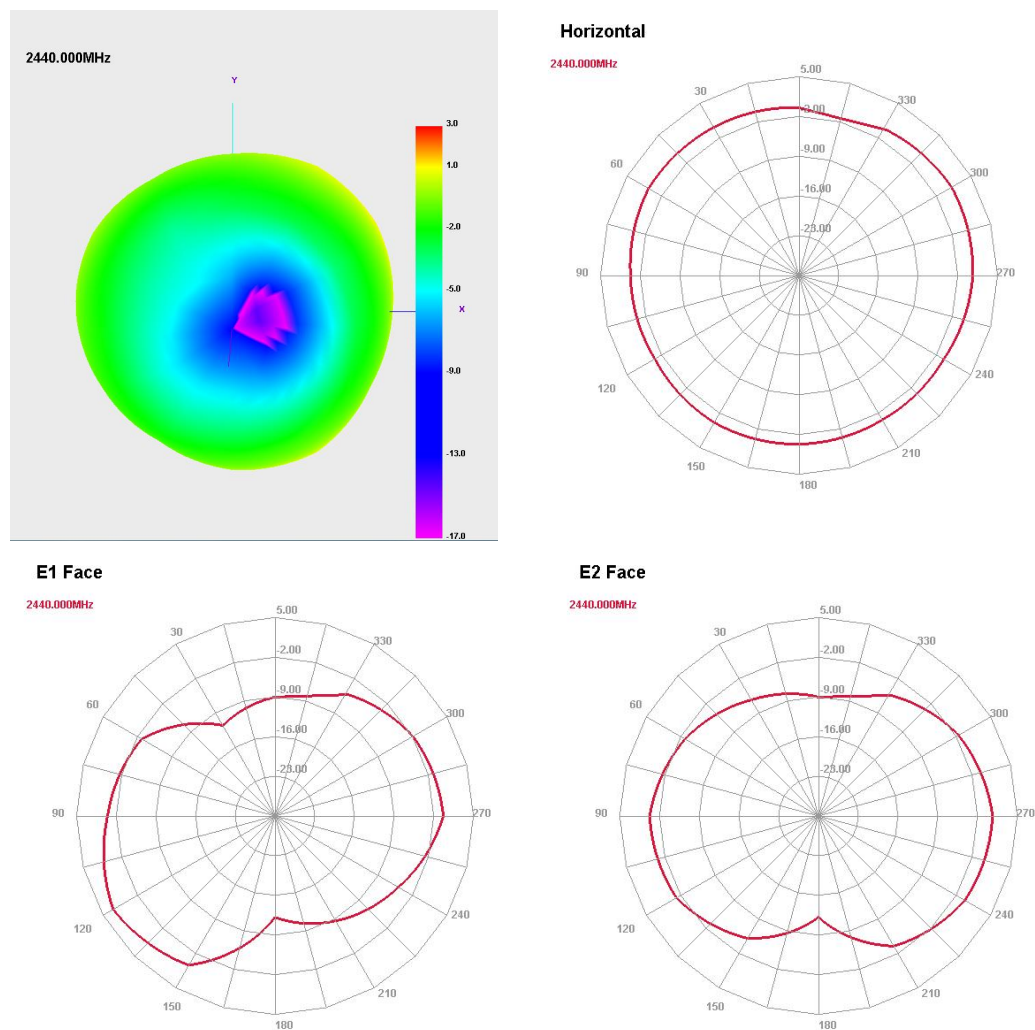
5.1 S11 Parameter



5.2 增益和效率 Gain & Efficiency

Freq (MHz)	Effi (%)	Effi (dB)	Gain dBi)
2400	66.92	-1.74	2.91
2410	69.87	-1.56	3.05
2420	68.35	-1.65	2.84
2430	72.35	-1.41	3.00
2440	71.47	-1.46	2.96
2450	74.2	-1.3	3.21
2460	70.94	-1.49	3.08
2470	65.84	-1.81	2.74
2480	59.56	-2.25	2.23

5.3 方向图 Radiation pattern



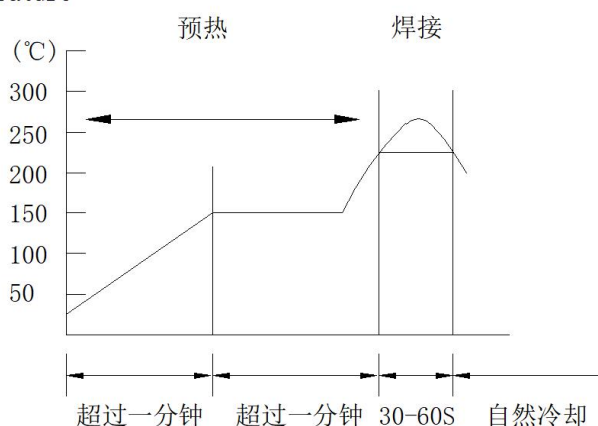
六、 推荐焊接温度曲线图 The temperature profile for soldering

6.1 回流焊接 (Re-flow soldering)

回流焊接

Temperature

温度



	Pb~Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230℃~250℃	240℃~260℃

预热时，请将焊接温度与元件表面温度之间的温差维持在 $T \leq 150^{\circ}\text{C}$ 。

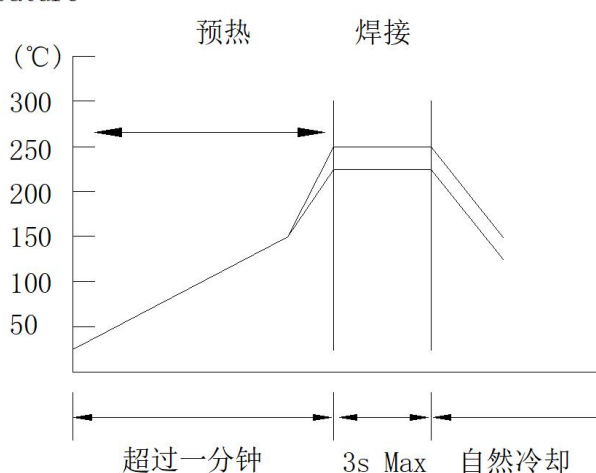
While in preheating, please keep the temperature difference between soldering temperature and surface

6.2 波峰焊接 (Wave soldering)

波峰焊接

Temperature

温度

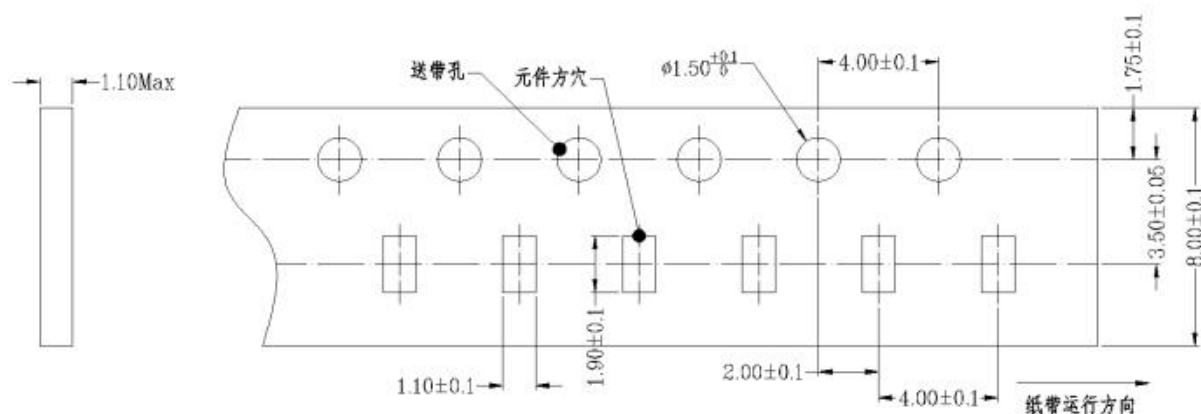


	Pb~Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230℃~260℃	240℃~270℃

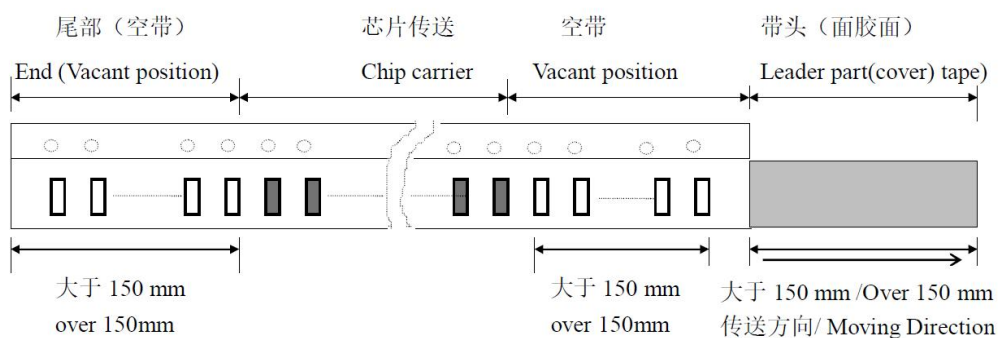
预热时，请将焊接温度与元件表面温度之间的温差维持在 $T \leq 150^{\circ}\text{C}$ 。

While in preheating, please keep the temperature difference between soldering temperature and surface

七、 纸带编号尺寸大小 Dimensions of paper taping

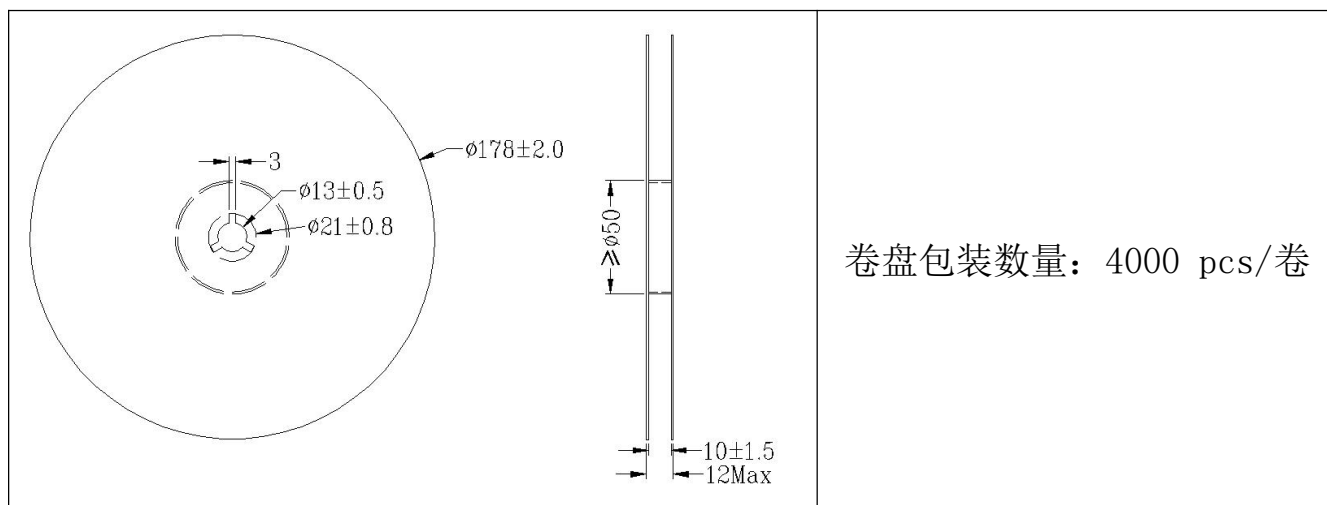


传送带的前后结构 Structure of leader part and end part of the carrier paper



八、产品包装 Product packaging

8.1 卷盘尺寸 Reel Dimensions (unit: mm)



8.2 纸箱包装

小包装数量: 10 卷 The first package Quantity: 10 reels	大包装数量: 6 盒 The second package Quantity: 6 cases